

USB Type-C® Analog Audio Switch with Protection Function

FSA4480

Description

FSA4480 is a high performance USB Type-C port multimedia switch which supports analog audio headsets. FSA4480 allows the sharing of a common USB Type-C port to pass USB2.0 signal, analog audio, sideband use wires and analog microphone signal. FSA4480 also supports high voltage on SBU port and USB port on USB Type-C receptacle side.

Features

- Power Supply: V_{CC}, 2.7 V to 5.5 V
- USB High Speed (480 Mbps) Switch:
 - ◆ SDD₂₁ –3dB bandwidth: 950 MHz
 - ♦ 3 Ω R_{ON} Typical
- · Audio Switch
 - ◆ Negative Rail Capability: -3 V to +3 V
 - \bullet THD+N = -110 dB; 1 V_{RMS}, f = 20 Hz \sim 20 kHz, 32 W Load
 - ♦ 1 Ω R_{ON} Typical
- High Voltage Protection
 - ◆ 20 V DC Tolerance on Connector Side Pins
 - ◆ Over Voltage Protection: V_{TH} = 5 V (Typ)
- OMTP and CTIA Pinout Support
- Support Audio Sense Path
- 25-Ball WLCSP Package (2.24 mm x 2.28 mm)

Applications

• Mobile Phone, Tablet, Notebook PC, Media Player

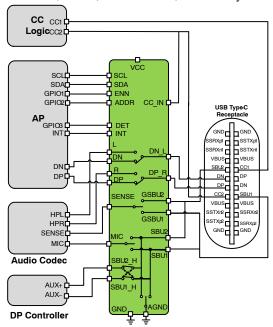


Figure 1. Application Block Diagram



MARKING DIAGRAM

6D&K &2&Z _oJ–PUU

6D = Specific Device Code

&K = 2-digits Lot Run Traceability Code

&2 = 2-digits Date Code (YW)

&Z = Assembly Location

J- = X- Coordinates with dash as separator*

P = Y Coordinates*

UU = Two Digit Wafer ID*

*For onsemi internal use only.

ORDERING INFORMATION

Part Number	Package	Marking
FSA4480UCX	WLCSP25	6D
	(Pb-Free)	

PIN CONFIGURATION

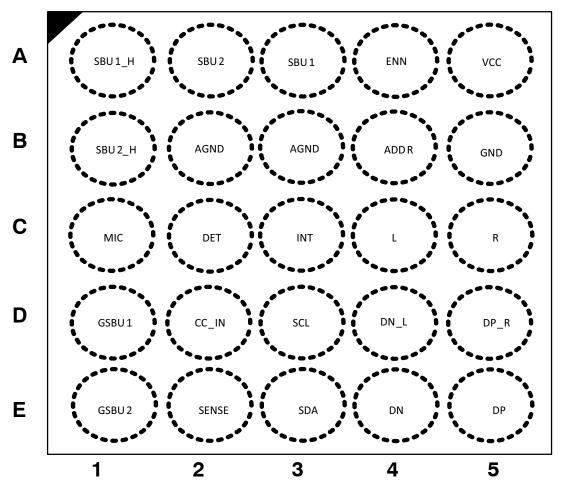


Figure 2. Pin Assignment (Top Through View)

Table 1. PIN DESCRIPTIONS

No.	Pin	Name	Description
1	A5	VCC	Power Supply (2.7 to 5.5 V)
2	B5	GND	Chip ground
3	D5	DP_R	USB/Audio Common Connector
4	D4	DN_L	USB/Audio Common Connector
5	E5	DP	USB Data (Differential +)
6	E4	DN	USB Data (Differential –)
7	C5	R	Audio – Right Channel
8	C4	L	Audio – Left Channel
9	АЗ	SBU1	Sideband use wire 1
10	A2	SBU2	Sideband use wire 2
11	C1	MIC	Microphone signal
12	B2	AGND	Audio signal ground
13	В3	AGND	Audio signal ground
14	E2	SENSE	Audio ground reference output
15	C3	INT	I ² C Interrupt output, active low (open drain)
16	D2	CC_IN	Audio accessory attachment detection input
17	D1	GSBU1	Audio sense path 1 to headset jack GND
18	E1	GSBU2	Audio sense path 2 to headset jack GND
19	C2	DET	Push-pull output. When CC_IN > 1.5 V, DET is low and CC_IN < 1.2 V, DET is high
20	D3	SCL	I ² C clock
21	E3	SDA	I ² C data
22	B1	SBU2_H	Host Side Sideband Use Wire 2
23	A1	SBU1_H	Host Side Sideband Use Wire 1
24	A4	ENN	Chip Enable, active low, internal pull-down by 470 kΩ
25	B4	ADDR	I ² C slave address pin

Table 2. ABSOLUTE MAXIMUM RATINGS

Symbol	Paramo	eter	Min.	Max.	Unit
V _{CC}	Supply Voltage from VCC		-0.5	6.5	V
V _{CC_IN}	V _{CC_IN,} to GND		-0.5	20	V
V _{SW_C}	V _{DP_R} to GND, V _{DN_L} to GND		-3.5	20	V
V _{SW_USB}	V _{DP} to GND, V _{DN} to GND	-0.5	6.5	V	
V _{SW_Audio}	V _L to GND, V _R to GND	-3.6	6.5	V	
V _{V_SBU/GSBU}	V_{SBU1} to GND, V_{SBU2} to GND, V_{GSBU1} to GNE), V _{GSBU1} to GND	-0.5	20	V
V _{VSBU_H}	VsBu1_H to GND, VsBu2_H to GND		-0.5	6.5	V
V _{I/O}	SENSE, MIC, DET, INT, to GND		-0.5	6.5	V
V _{CNTRL}	Control Input Voltage	-0.5	6.5	V	
I _{SW_Audio}	Switch I/O Current, Audio Path		-250	250	mA
I _{SW_USB}	Switch I/O Current, USB Path	_	100	mA	
I _{SW_MIC}	Switch I/O Current, MIC to SBU1 or SBU2	_	50	mA	
I _{SW_SBU}	Switch I/O Current, SBUx to SBUx_H		_	50	mA
I _{SW_SENSE}	Switch I/O Current, SENSE to GSBU1 or GSB	U2	_	100	mA
I _{SW_AGND}	Switch I/O Current, AGND to SBU1 or SBU2		_	500	mA
I _{IK}	DC Input Diode Current		-50	_	mA
ESD	Human Body Model, ANSI/ESDA/JEDEC JS-001-2012	Connector side and power pins: VCC, SBU1, SBU2, DP_R, DN_L, GSBU1, GSBU2, CC_IN	4	-	kV
ESD	Human Body Model, ANSI/ESDA/JEDEC JS-001-2012	DEC Host side pins: the rest pins		_	kV
ESD	Charged Device Model, JEDEC: JESD22-C10	1	1	-	kV
T _A	Absolute Maximum Operating Temperature		-40	85	°C
T _{STG}	Storage Temperature		-65	150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
POWER					
V_{CC}	Supply Voltage	2.7	_	5.5	V
USB SWITCH					
V _{SW_USB}	V_{DP} to GND, V_{DN} to GND, V_{DP_R} to GND, V_{DN_L} to GND	0	-	3.6	V
AUDIO SWITC	н				
V_{SW_Audio}	V_{DP_R} to GND, V_{DN_L} to GND, V_L to GND, V_R to GND	-3.6	=	3.6	V
MIC SWITCH					
V _{VSBU_MIC}	V _{SBU1} to GND, V _{SBU2} to GND, V _{MIC} to GND	0	-	3.6	V
SENSE SWITC	н				
V _{VGSBU_SEN}	V _{GSBU1} to GND, V _{GSBU2} to GND, V _{SENSE} to GND	0	-	3.6	V
SBU TO SBUX	_H SWITCH				
V _{VGSBU}	V_{SBU1} to GND, V_{SBU2} to GND, V_{SBU1_H} to GND, V_{SBU2_H} to GND	0	-	3.6	V
CC_IN PIN					
V _{CC_IN}	V _{CC_IN,} to GND	0	-	5.5	V
CONTROL VO	LTAGE (ENN/SDA/SCL)				
V _{IH}	Input Voltage High	1.3	-	V _{CC}	V
V _{IL}	Input Voltage Low	-	-	0.5	V
OPERATING T	EMPERATURE	-			
T _A	Ambient Operating Temperature	-40	25	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. DC ELECTRICAL CHARACTERISTICS

 $(V_{CC}$ = 2.7 V to 5.5 V, V_{CC} (Typ.) = 3.3 V, T_A = -40°C to 85°C, and T_A (Typ.) = 25°C, unless otherwise specified.)

Symbol	Parameter	Condition	Power	Min.	Тур.	Max.	Unit
I _{CC}	Supply Current	USB switches on, SBUx to SBUx_H switches on	V _{CC} : 2.7 V to 5.5 V	_	-	65	μА
		Audio switches on, MIC switch on and Audio GND switch on		-	_	60	μΑ
I _{CCZ}	Quiescent Current	ENN = L, 04H'b7 = 0		-	-	5	μΑ
USB/AUDIO	COMMON PINS: DP/R, DN_L		•				<u>. </u>
I _{OZ}	Off Leakage Current of DP_R and DN_L	DN_L, DP_R = -3 V to 3.6 V	V _{CC} : 2.7 V to 5.5 V	-3.0	_	3.0	μΑ
l _{OFF}	Power-Off Leakage Current of DP_R and DN_L	DN_L, DP_R = 0 V to 3.6 V	Power off	-3.0	_	3.0	μΑ
V _{OV_TRIP}	Input OVP Lockout	Rising edge	V _{CC} : 2.7 V to 5.5 V	4.5	5	5.3	٧
V _{OV_HYS}	Input OVP Hysteresis			_	0.3	-	V
AUDIO SWIT	СН		•				
I _{ON}	On Leakage Current of Audio Switch	DN_L, DP_R = -3 V to 3.0 V, DP, DN, R, L = Float	V _{CC} : 2.7 V to 5.5 V	-2.5	_	2.5	μΑ
l _{OFF}	Power-Off Leakage Current of L and R	L, R = 0 V to 3 V; DP_R, DN_L = Float	Power off	-1.0	-	1.0	μΑ
R _{ON_AUDIO}	Audio Switch On Resistance	$I_{SW} = 100 \text{ mA}, V_{SW} = -3 \text{ V to 3 V}$	V _{CC} : 2.7 V to 5.5 V	-	1.0	2.1	Ω
R _{SHUNT}	Pull Down Resistor on R/L Pin when Audio Switch is Off	L = R = 3 V		6	10	14	kΩ
USB SWITCI	H						
I _{ON}	On Leakage Current of USB Switch	DN_L, DP_R = 0 V to 3.6 V, DP, DN, R, L = Float	V _{CC} : 2.7 V to 5.5 V	-3.0	-	3.0	μΑ
l _{OZ}	Off Leakage Current of DP and DN	DN, DP = 0 V to 3.6 V		-3.0	-	3.0	μΑ
l _{OFF}	Power-Off Leakage Current of DP and DN	DN, DP = 0 V to 3.6 V	Power off	-3.0	-	3.0	μΑ
R _{ON_USB}	USB Switch On Resistance	I _{SW} = 8 mA, V _{SW} = 0.4 V	V _{CC} : 2.7 V to 5.5 V	_	3.0	5.2	Ω
SENSE SWIT	гсн						
I _{ON}	Sense Path Leakage Current	GSBUx = 0 V to 1 V, SENSE is floating	V _{CC} : 2.7 V to 5.5 V	-2.0	-	2.0	μΑ
R _{ON_SENSE}	SENSE Switch On Resistance	I _{SW} = 100 mA, Vsw = 1 V	V _{CC} : 2.7 V to 5.5 V	0.20	0.30	0.40	Ω
I _{OZ}	Off Leakage Current of SENSE	Sense = 0 V to 1.0 V		-2.0	_	2.0	μΑ
	Off Leakage Current of GSBUx	GSBUx = 0 V to 1.0 V		-2.0	-	2.0	μА
		GSBUx = 1 V to 3.6 V	1	-3.0	_	3.0	1
I _{OFF}	Power-Off Leakage Current of SENSE	Sense = 0 V to 1.0 V	Power off	-2.0	-	2.0	μА
	Power-Off Leakage Current of GSBUx	GSBUx = 0 V to 3.6 V	1	-3.0	_	3.0	

Table 4. DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, V_{CC} \text{ (Typ.)} = 3.3 \text{ V}, T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}, \text{ and } T_A \text{ (Typ.)} = 25^{\circ}\text{C}, \text{ unless otherwise specified.})$

Symbol	Parameter	Condition	Power	Min.	Тур.	Max.	Unit
SENSE SWIT	гсн						
V _{OV_TRIP}	Input OVP Lockout on GSBUx	Rising edge	V _{CC} : 2.7 V to 5.5 V	4.5	5	5.3	V
V _{OV_HYS}	Input OVP Hysteresis of GSBUx			-	0.3	-	V
SBUX PINS			_				
I _{OZ}	Off Leakage Current of SBUx	SBUx = 0 V to 3.6 V V _{CC} : 2.7 V to 5.5 V		-3.0	-	3.0	μΑ
I _{OFF}	Power-Off Leakage Current Port SBUx	SBUx = 0 V to 3.6 V	SBUx = 0 V to 3.6 V Power off -		-	3.0	μΑ
V _{OV_TRIP}	Input OVP Lockout	Rising edge	V _{CC} : 2.7 V to 5.5 V	4.5	5	5.3	V
V _{OV_HYS}	Input OVP Hysteresis			-	0.3	-	٧
MIC SWITCH	ł						
I _{ON}	On Leakage Current of MIC Switch	SBUx = 0 V to 3.6 V, MIC is floating	V _{CC} : 2.7 V to 5.5 V	-3.0	_	3.0	μΑ
I _{OZ}	Off Leakage Current of MIC	MIC = 0 V to 3.6 V		-1.0	_	1.0	μΑ
I _{OFF}	Power Off Leakage Current of MIC	MIC = 0 V to 3.6 V	Power off	-1.0	-	1.0	μΑ
R _{ON_MIC}	MIC Switch On Resistance	Isw = 30 mA, Vsw = 3.6 V	V _{CC} : 2.7 V to 5.5 V	1.7	3.0	3.9	Ω
SBUX_H SW	/ITCH						
I _{ON}	On Leakage Current of SBUx_H Switch	SBUx = 0 V to 3.6 V, SBUx_H is floating	V _{CC} : 2.7 V to 5.5 V	-3.0	-	3.0	μΑ
I _{OZ}	Off Leakage of SBUx_H	SBUx_H =0 V to 3.6 V		-1	-	1	μΑ
I _{OFF}	Power Off Leakage Current of SBUx_H	SBUx_H = 0 V to 3.6 V	Power off	-1.0	-	1.0	μΑ
R _{ON_SBU}	SBUx_H Switch On Resistance	Isw = 30 mA, V _{SW} = 0 V to 3.6 V	V _{CC} : 2.7 V to 5.5 V	1.5	3.0	3.5	Ω
AUDIO GRO	UND SWITCH: PIN: AGND TO SB	UX					
R _{ON_AGND}	AGND Switch On Resistance	I _{SOURCE} = 100 mA on SBUx	V _{CC} : 2.7 V to 5.5 V	30	50	90	mΩ
CC_IN PIN							
V _{TH_L}	Input Low Threshold		V _{CC} : 2.7 V to 5.5 V	_	1.2	_	V
V _{TH_H}	Input High Threshold			_	1.5	_	V
I _{IN}	Input Leakage of CC_IN	CC_IN = 0 V to 5.5 V		_	_	1.0	μΑ
INT, DET PIN	IS						
V _{OH}	Output High for DET	lo = −2 mA	V _{CC} : 2.7 V to 5.5 V	1.5	1.8	2	V
V _{OL}	Output Low for DET and INT	lo = 2 mA		_	-	0.4	V

Table 4. DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, V_{CC} \text{ (Typ.)} = 3.3 \text{ V}, T_A = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C}, \text{ and } T_A \text{ (Typ.)} = 25^{\circ}\text{C}, \text{ unless otherwise specified.})$

Symbol	Parameter	Condition	Power	Min.	Тур.	Max.	Unit
ADDR PIN	•		•				
V_{IH}	Input voltage High		V _{CC} : 2.7 V to 5.5 V	1.3	-	_	٧
V_{IL}	Input voltage Low			_	-	0.45	٧
I _{IN}	Control Input Leakage ADDR = 0 V to V _{CC}			-1	-	1	μΑ
ENN PIN			•				
V_{IH}	Input Voltage High		V _{CC} : 2.7 V to 5.5 V	1.3	-	-	٧
V_{IL}	Input Voltage Low			_	-	0.45	٧
R _{PD}	Internal Pull Down Resistor			-	470	-	kΩ
SDS, SCL P	INS	•					
V _{ILI2C}	Low-Level Input Voltage		V _{CC} : 2.7 V to 5.5 V	_	-	0.4	٧
V _{IHI2C}	High-Level Input Voltage			1.2	-	-	V
I _{I2C}	Input Current of SDA and SCL Pins	SCL/SDA = 0 V to 3.6 V		-2	-	2	μΑ
V _{OLSDA}	Low-Level Output Voltage	I _{OL} = 2 mA		_	-	0.3	V
I _{OLSDA}	Low-Level Output Current	V _{OLSDA} = 0.2 V		10	-	-	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 5. AC ELECTRICAL CHARACTERISTICS

 $(V_{CC}$ = 2.7 V to 5.5 V, V_{CC} (Typ.) = 3.3 V, T_A = -40°C to 85°C, and T_A (Typ.) = 25°C, unless otherwise specified.)

Symbol	Parameter	Condition	Power	Min.	Тур.	Max.	Unit
AUDIO SWITCH	1	·	l				
t _{delay}	Audio Switch Turn On Delay Time	DP_R = DN_L = 1 V, R _L = 32 Ω	V _{CC} = 3.3 V	-	65	-	μs
t _{rise}	Audio Switch Turn On Rising Time (Note 1)	$ \begin{array}{l} DP_R = DN_L = 1 \; V, \\ R_L = 32 \; \Omega \end{array} $		_	240	-	μs
t _{OFF}	Audio Switch Turn Off Time	$\begin{array}{l} \text{DP_R} = \text{DN_L} = 1 \text{ V}, \\ \text{R}_{\text{L}} = 32 \ \Omega \end{array}$		_	15	_	μs
X _{TALK}	Cross Talk (Adjacent)	$f = 1 \text{ kHz}, R_L = 50 \Omega,$ $V_{SW} = 1 V_{RMS}$		-	-100	-	dB
BW	−3 dB Bandwidth	R _L = 50 Ω		_	600	_	MHz
O _{IRR}	Off Isolation	F = 1 kHz, RL = 50 Ω, CL = 0 pF, Vsw = 1 VRMs		-	-100	-	dB
THD+N	Total Harmonic Distortion + Noise Performance with A-weighting Filter	$R_L = 600 \ \Omega, f = 20 \ Hz \sim 20 \ kHz, \ V_{SW} = 2 \ V_{RMS}$		-	-110	-	dB
		R_L = 32 Ω , f = 20 Hz~20 kHz, V_{SW} = 1 V_{RMS}		_	-110	-	dB
		R_L = 16 Ω , f = 20 Hz~20 kHz, V_{SW} = 0.5 V_{RMS}		_	-108	-	dB
USB SWITCH							
t _{ON}	USB Switch Turn-on Time	$DP_R = DN_L = 1.5 \text{ V},$ $R_L = 50 \Omega$	V _{CC} = 3.3 V	-	60	-	μs
t _{OFF}	USB Switch Turn -off Time	$\begin{aligned} &DP_R = DN_L = 1.5 \text{ V}, \\ &R_L = 50 \Omega \end{aligned}$		-	15	-	μS
BW	–3 dB Bandwidth	$R_L = 50 \Omega$		_	850	_	MHz
	SDD ₂₁ –3 dB Bandwidth			_	950	_	1
O _{IRR}	Off Isolation between DP, DN and Common Node Pins	$ f = 1 \text{ kHz}, \ R_L = 50 \ \Omega, \ C_L = 0 \ pF, \\ V_{SW} = 1 \ V_{RMS} $		_	-100	_	dB
t _{OVP}	DP_R and DN_L pins OVP Response Time	Vsw = 3.5 V to 5.5 V		_	1	1.5	μs
MIC/AUDIO GR	OUND SWITCH						
t _{delay_MIC}	MIC Switch Turn On Delay Time	SBUx = 1 V, R_L = 50 Ω	V _{CC} = 3.3 V	_	100	_	μs
t _{rise_MIC}	MIC Switch Turn On Rising Time (Note 1)			-	250	-	
t _{delay_AGND}	AGND Switch Turn On Time	SBUx pulled up to 0.5 V by	V _{CC} = 3.3 V	_	100	_	μs
t _{rise_} AGND	AGND Switch Turn On Rising Time (Note 1)	16 Ω, AGND connect to GND		_	1500	-	
t _{OFF_MIC}	MIC Switch Turn Off Time	SBUx = 2.5 V, R_L = 50 Ω		_	15	_	
OFF_Audio GND	AGND Switch Turn Off Time	SBUx: Isource = 10 mA, clamp to 2.5 V		-	15	-	
			4				

Table 5. AC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, V_{CC} \text{ (Typ.)} = 3.3 \text{ V}, T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}, \text{ and } T_A \text{ (Typ.)} = 25^{\circ}\text{C}, \text{ unless otherwise specified.})$

Symbol	Parameter	Condition	Power	Min.	Тур.	Max.	Unit
SBUX_H SWIT	гсн	•					
t _{ON}	SBUx_H Switch Turn On Time	SBUx = 2.5 V, R_L = 50 Ω	V _{CC} = 3.3 V	-	35	_	μs
toff	SBUx_H Switch Turn Off Time			_	15	_	
BW	Bandwidth	R _L = 50 Ω		-	50		MHz
t _{OVP}	SBUx Pins OVP Response Time	Vsw = 3.5 V to 5.5 V		-	0.5	1	μs
SENSE SWITC	ЭН		•				
t _{delay}	Sense Switch Turn On Delay Time	GSBUx = 1 V, R_L = 50 Ω	V _{CC} = 3.3 V	-	65	_	μs
t _{rise}	Sense Switch Turn On Rising Time (Note 1)			-	260	-	μs
toff	Sense Switch Turn Off Time			_	15	_	μs
t _{OVP}	GSBUx Pins OVP Response Time	V _{SW} : 3.5 V to 5.5 V		_	0.7	1.5	μs
BW	Bandwidth	R _L = 50 Ω		-	150	_	MHz
DET DELAY	•						
t _{DELAY_DET}	DET Response Delay	Transition from 0 to 1.8 V	V _{CC} = 3.3 V	-	1	_	μs
		Transition from 1.8 to 0 V		-	5	-	1

^{1.} Turn on timing can be controlled by I²C register.

Table 6. I²C SPECIFICATION

 $(V_{CC}=2.7~V~to~5.5,~V_{CC}~(Typ.)=3.3~V~, T_{A}=-40^{\circ}C~to~85^{\circ}C.~T_{A}~(Typ.)=25^{\circ}C,~unless~otherwise~specified)$

			Fast Mode	
Symbol	Parameter	Min.	Max.	Unit
f _{SCL}	I ² C_SCL Clock Frequency		400	kHz
t _{HD; STA}	Hold Time (Repeated) START Condition	0.6		μs
t _{LOW}	Low Period of I ² C_SCL Clock	1.3		μs
t _{HIGH}	High Period of I ² C_SCL Clock	0.6		μs
t _{SU; STA}	Set-up Time for Repeated START Condition	0.6		μs
t _{HD; DAT}	Data Hold Time (Note 2)	0	0.9	μs
t _{SU; DAT}	Data Set-up Time (Note 3)	100		ns
t _r	Rise Time of I ² C_SDA and I ² C_SCL Signals (Note 3)	20 + 0.1C _b	300	ns
t _f	Fall Time of I ² C_SDA and I ² C_SCL Signals (Note 3)	20 + 0.1C _b	300	ns
t _{SU; STO}	Set-up Time for STOP Condition	0.6		μs
t _{BUF}	Bus-Free Time between STOP and START Conditions	1.3		μs
t _{SP}	Pulse Width of Spikes that Must Be Suppressed by the Input Filter	0	50	ns

Guaranteed by design, not production tested.
 A fast-mode I²C-bus device can be used in a standard-mode I²C-bus system, but the requirement t_{SU;DAT} ≥ ±250 ns must be met. This is automatically the case if the device does not stretch the LOW period of the I2C_SCL signal. If such a device does stretch the LOW period of the I²C_SCL signal, it must output the next data bit to the I²C_SDA line t_{r_max} + t_{SU;DAT} = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the I²C_SCL line is released.

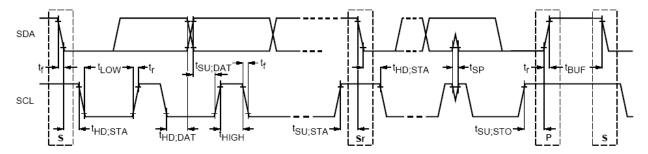


Figure 3. Definition of Timing for Full-Speed Mode Devices on the I²C Bus

Table 7. CAPACITANCE

(V_{CC}= 2.7 V to 5.5 V, V_{CC} (Typ.) = 3.3 V, T_A = -40° C to 85°C, and T_A (Typ.) = 25°C)

				T _A =-				
Symbol	Parameter	Condit	ion	Power	Min.	Тур.	Max.	Unit
C _{ON_USB/Audio}	On Capacitance ⁽⁶⁾ (Common Port)	f = 1 MHz, 100 mV _{PK} . bias	_{-PK} , 100 mV DC	VCC = 3.3 V		9		pF
C _{OFF_USB/Audio}	Off Capacitance ⁽⁶⁾ (Common Port)	f = 1 MHz, 100 mV _{PK} . bias			7.5		pF	
C _{OFF_USB}	Off Capacitance (Non-Common Ports) (6)	f = 1 MHz, 100 mV _{PK} . bias			3		pF	
C _{ON_SENSE_SW}	On Capacitance – (Common Ports) ⁽⁶⁾	f = 1 MHz, 100 mV _{PK} . DC bias			55		pF	
C _{OFF_SENSE_SW}	Off Capacitance – (Common Ports) ⁽⁶⁾	f = 1 MHz, 100 mV _{PK} . DC bias	f = 1 MHz, 100 mV _{PK-PK} , 100 mV DC bias					pF
C _{ON_MIC_SW}	On Capacitance – (Common Ports) ⁽⁶⁾	f = 1 MHz, 100 mV _{PK} . DC bias	_{-PK} , 100 mV			170		pF
C _{OFF_MIC_SW}	Off Capacitance – (Common Ports) ⁽⁶⁾	f = 1 MHz, 100 mV _{PK} . DC bias	_{-PK} , 100 mV			10		pF
C _{ON_AGND_SW}	On Capacitance ⁽⁶⁾ (Common Port)	f = 1 MHz, 100 mV _{PK} . DC bias	_{-PK} , 100 mV			125		pF
C _{ON_SBUx_H_SW}	On Capacitance ⁽⁶⁾ (Common Port)	f = 1 MHz, 100 mV _{PK} . DC bias			160		pF	
C _{CNTRL}	Control Input Pin Capacitance ⁽⁶⁾	f = 1 MHz, 100 mV _{PP} , 100 mV DC bias	ENN			3		pF

Table 8. REGISTER MAPS

ADDR	Register Name	Туре	Reset Value	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0
00H	Device ID	R	0x09	0	0	0	0	1	0	0	1
01H	OVP Interrupt Mask	R/W	0x00	Reserved	Mask OVP interrupt	Mask OVP /DP_R	Mask OVP /DN_L	Mask OVP /SBU1	Mask OVP /SBU2	Mask OVP /GSBU1	Mask OVP /GSBU2
02H	OVP interrupt flag	R/C	0x00	Rese	rved	DP_R	DN_L	SBU1	SBU2	GSBU	GSBU2
03H	OVP status	R	0x00	Rese	rved	OVP/ DP_R	OVP/ DN_L	OVP/SB U1	OVP/SB U2	OVP/ GSBU1	OVP/ GSBU2
04H	Switch settings Enable	R/W	0x98	Device control	SBU1_H to SBUx	SBU2_H to SBUx	DN_L to DN or L	DP_R to DP or R	Sense to GSBUx	MIC to SBUx	Audio Ground to SBUx
05H	Switch select	R/W	0x18	Reserved	SBU1_H to SBUx	SBU2_H to SBUx	DN_L to DN or L	DP_R to DP or R	Sense to GSBUx	MIC to SBUx	Audio Ground to SBUx
06H	Switch Status0	R	0x00	Rese	rved	Sense Sw	itch Status	DP_R Swi	tch Status	DN_L Swi	tch Status
07H	Switch Status1	R	0x00	Rese	rved	SE	SU2 Switch Sta	tus	SB	U1 Switch Sta	tus
08H	Audio Switch Left Channel turn on Control	R/W	0x01			Audio	switch left chan	nel slow contro	ol [7:0]		
09H	Audio Switch Right Channel turn on Control	R/W	0x01			Audio s	witch right chai	nnel slow contr	ol [7:0]		
0AH	MIC switch turn on control	R/W	0x01			MIC sv	vitch right chan	nel slow contro	ol [7:0]		
0BH	Sense switch turn on control	R/W	0x01	Sense switch right channel slow control [7:0]							
0CH	Audio Ground Switch turn on Control	R/W	0x01	Audio ground switch right channel slow control [7:0]							

Table 8. REGISTER MAPS

ADDR	Register Name	Туре	Reset Value	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	ВІТО
0DH	Timing Delay between R switch enable and L switch enable	R/W	0x00	Timing Delay between R switch enable and L switch enable control [7:0]							
0EH	Timing Delay between MIC switch enable and L switch enable	R/W	0x00		Timing Delay between MIC switch enable and L switch enable control [7:0]						
0FH	Timing Delay between Sense switch enable and L switch enable	R/W	0x00		Timing Do	elay between S	Sense switch er	nable and L sw	itch enable cor	ntrol [7:0]	
10H	Timing Delay between Audio ground switch enable and L switch enable	R/W	0x00		Timing Delay	between Audi	o ground switch	h enable and L	switch enable	control [7:0]	
11H	Audio accessory status	R	0x02			Rese	rved			CC_IN	DET
12H	Function enable	R/W	0x08	Reserved	DET I/O Control	RES detection range setting	GIPO control	SLOW TURN-O N CONTR OLL	MIC auto control	RES detection : auto clear	Audio jack detection : auto clear
13H	RES detection pin setting	R/W	0x00		Reserved Detect				ction pin selec	t [2:0]	
14H	RES detection value	R	0xFF	R detection value [7:0]							
15H	RES detection interrupt threshold	R/W	0x16			R detecti	on Interrupt res	sistance thresh	old [7:0]		
16H	RES detection interval	R/W	0X00			Rese	rved			Detection is	nterval [1:0]
17H	Audio jack Status	RO	0x01		Rese	rved		4pole,SB U2 MIC	4pole,SB U1 MIC	3pole	No audio
18H	Detection interrupt	R/C	0x00			Reserved			Audio detection done	RES detection occurred	RES detection done
19H	Detection interrupt Mask	R/W	0x00	Reserved Audio detection done mask				RES detection occurred mask	RES detection done mask		
1AH	Audio detection RGE1	RO	0xFF	audio detection value REG1 [7:0]							
1BH	Audio detection RGE2	RO	0xFF	audio detection value REG2 [7:0]							
1CH	MIC Threshold DATA0	R/W	0x20	MIC Threshold value DATA0 [7:0]							
1DH	MIC Threshold DATA1	R/W	0xFF		MIC Threshold value DATA1 [7:0]						
1EH	I2C Reset	W/C	0x00				Reserved				I2C reset
1FH	Current Source Setting	R/W	0x07		Rese	rved			Current Source	e setting [3:0]	

Table 9. I²C SLAVE ADDRESS

ADDR	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ADDR = L	1	0	0	0	0	1	0	R/W
ADDR = H	1	0	0	0	0	1	1	R/W

DEVICE ID

Address: 00h

Reset Value: 8'b 0000_1001

Type: Read

Bits	Name	Size	Description
7:6	Vendor ID	2	Vendor ID
5:3	Version ID	3	Device Version ID
2:0	Revision ID	3	Revision History ID

OVP INTERRUPT MASK

Address: 01h

Reset Value: 8'b 0000_0000

Type: Read/Write

Bits	Name	Size	Description
7	Reserved	1	Do Not Use
6	OVP Interrupt mask control	1	OVP Interrupt function Enable/Disable 0: Controlled by [5:0] bit 1: Mask all connector side pins OVP interrupt
5	DP_R OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
4	DN_L OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
3	SBU1 OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
2	SBU2 OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
1	GSBU1 OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
0	GSBU2 OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt

OVP INTERRUPT FLAG

Address: 02h

Reset Value: 8'b 0000_0000

Type: Read Clear

Bits	Name	Size	Description
[7:6]	Reserved	2	Do Not Use
5	DP_R OVP	1	OVP event has not occurred OVP event has occurred
4	DN_L OVP	1	OVP event has not occurred OVP event has occurred
3	SBU1 OVP	1	OVP event has not occurred OVP event has occurred
2	SBU2 OVP	1	OVP event has not occurred OVP event has occurred
1	GSBU1 OVP	1	OVP event has not occurred OVP event has occurred
0	GSBU2 OVP	1	0: OVP event has not occurred 1: OVP event has occurred

OVP STATUS

Address: 03h

Reset Value: 8'b 0000_0000

Type: Read

Bits	Name	Size	Description
[7:6]	Reserved	2	Do Not Use
5	OVP on DP_R PIN	1	0: OVP event has not occurred 1: OVP event has occurred
4	OVP on DN_L PIN	1	0: OVP event has not occurred 1: OVP event has occurred
3	OVP on SBU1 PIN	1	0: OVP event has not occurred 1: OVP event has occurred
2	OVP on SBU2 PIN	1	0: OVP event has not occurred 1: OVP event has occurred
1	OVP on GSBU1 PIN	1	0: OVP event has not occurred 1: OVP event has occurred
0	OVP on GSBU2 PIN	1	0: OVP event has not occurred 1: OVP event has occurred

SWITCHING SETTING ENABLE

Address: 04h

Reset Value: 8'b 1001_1000 Type: Read/Write

Bits	Name	Size	Description
7	Device Enable	1	O: Device Disable; L, R pull down by 10 k and other switch nodes will be high–Z for positive input. 1: Device Enable. Device Enable = 1 Device enable = 0 ENN = 1 Device Disable ENN = 0 Device Enable Device Disable
6	SBU1_H to SBUx switches	1	0: Switch Disable; SBU1_H will be high-Z for positive input 1: Switch Enable
5	SBU2_H to SBUx switches	1	0: Switch Disable; SBU2_H will be high-Z for positive input 1: Switch Enable
4	DN_L to DN or L switches	1	Switch Disable; DN_L,DN will be high-Z for positive input. L pull down by 10 kohm Switch Enable
3	DP_R to DP or R switches	1	O: Switch Disable; DP_R,DP will be high-Z for positive input. R pull down by 10 kohm 1: Switch Enable
2	Sense to GSBUx switches	1	Switch Disable; Sense,GSBU1 and GSBU2 will be high-Z for positive input Switch Enable
1	MIC to SBUx switches	1	Switch Disable: MIC will be high-Z for positive input. Switch Enable
0	AGND to SBUx switches	1	Switch Disable: AGND will be high-Z for positive input. Switch Enable

SWITCH SELECT

Address: 05h

Reset Value: 8'b 0001_1000

Type: Read/Write

Bits	Name	Size	Description
7	Reserved	1	Do Not Use
6	SBU1_H switches	1	0: SBU1_H to SBU1 switch ON 1: SBU1_H to SBU2 switch ON
5	SBU2_H switches	1	0: SBU2_H to SBU2 switch ON 1: SBU2_H to SBU1 switch ON
4	DN_L to DN or L switches	1	0: DN_L to L switch ON 1: DN_L to DN switch ON
3	DP_R to DP or R switches	1	0: DP_R to R switch ON 1: DP_R to DP switch ON
2	Sense to GSBUx switches	1	0: Sense to GSBU1 switch ON 1: Sense to GSBU2 switch ON
1	MIC to SBUx switches	1	0: MIC to SBU2 switch ON 1: MIC to SBU1 switch ON
0	AGND to SBUx switches	1	0: AGND to SBU1 switch ON 1: AGND to SBU2 switch ON

SWITCH STATUS0

Address: 06h

Reset Value: 8'b 0000_0000

Type: Read Only

Bits	Name	Size	Description
[7:6]	Reserved	2	Do not use
[5:2]	Sense Switch Status	2	00: Sense switch is Open/Not Connected 01: Sense connected to GSBU1 10: Sense connected to GSBU2 11: Not Valid
[3:2]	DP_RSwitch Status	2	00: DP_R Switch Open/Not Connected 01: DP_Rconnected to DP 10: DP_Rconnected to R 11: Not Valid
[1:0]	DN_L switch Status	2	00: DN_L Switch Open/Not Connected 01: DN_L connected to DN 10: DN_L connected to L 11: Not Valid

SWITCH STATUS1

Address: 07h

Reset Value: 8'b 0000_0000

Type: Read Only

Bits	Name	Size	Description
[7:6]	Reserved	2	Do not use
[5:3]	SBU2 Switch Status	3	000: SBU2 switch is Open/Not Connected 001: SBU2 connected to MIC 010: SBU2 connected to AGND 011: SBU2 connected to SBU1_H 100: SBU2 connected to SBU2_H 101: SBU2 connected both SBU1_H and SBU2_H 110111: Do not use
[2:0]	SBU1 Switch Status	3	000: SBU1 switch is Open/Not Connected 001: SBU1 connected to MIC 010: SBU1 connected to AGND 011: SBU1 connected to SBU1_H 100: SBU1 connected to SBU2_H 101: SBU1 connected both SBU1_H and SBU2_H 110111: Do not use

AUDIO SWITCH LEFT CHANNEL SLOW TURN-ON

Address: 08h

Reset Value: 8'b 0000_0001

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Switch turn on rising time setting	8	11111111: 25600 μS
			00000001: 200 μS
			00000000: 100 μS

AUDIO SWITCH RIGHT CHANNEL SLOW TURN-ON

Address: 09h

Reset Value: 8'b 0000 0001

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Switch turn on rising time setting	8	11111111: 25600 μS
			00000001: 200 μS
			00000000: 100 μS

MIC SWITCH SLOW TURN-ON

Address: 0Ah

Reset Value: 8'b 0000_0001

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Switch turn on rising time setting	8	111111111: 25700 μS
			00000010: 350 μS
			00000001: 250 μS
			00000000: Not Valid

SENSE SWITCH SLOW TURN-ON

Address: 0Bh

Reset Value: 8'b 0000_0001

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Switch turn on rising time setting	8	11111111: 25600 μS
			00000001: 200 μS
			00000000: 100 μS

AUDIO GROUND SWITCH SLOW TURN-ON

Address: 0Ch

Reset Value: 8'b 0000_0001

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Switch turn on rising time setting	8	11111111: 179000 μS
			00000001: 1400 μS
			00000000: 700 μS

TIMING DELAY BETWEEN R SWITCH ENABLE AND L SWITCH ENABLE

Address: 0Dh

Reset Value: 8'b 0000_0000

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Delay timing setting	8	11111111: 25500 μS
			11111110: 25400 μS
			00000001: 100 μS
			00000000: 0 μS

TIMING DELAY BETWEEN MIC SWITCH ENABLE AND L SWITCH ENABLE

Address: 0Eh

Reset Value: 8'b 0000_0000

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Delay timing setting	8	11111111: 25500 μS
			11111110: 25400 μS
			00000001: 100 μS
			00000000: 0 μS

TIMING DELAY BETWEEN SENSE SWITCH ENABLE AND L SWITCH ENABLE

Address: 0Fh

Reset Value: 8'b 0000_0000

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Delay timing setting	8	11111111: 25500 μS
			11111110: 25400 μS
			00000001: 100 μS
			00000000: 0 μS

TIMING DELAY BETWEEN AUDIO GROUND SWITCH ENABLE AND L SWITCH ENABLE

Address: 10h

Reset Value: 8'b 0000_0000

Type: Read/Write

Bits	Name	Size	Description
[7:0]	Delay timing setting	8	11111111: 25500 μS
			11111110: 25400 μS
			00000001: 100 μS
			00000000: 0 μS

AUDIO ACCESSORY STATUS

Address: 11h

Reset Value: 8'b 0000_0010

Type: Read

Bits	Name	Size	Description
[7:2]	Reserved	6	Do not use
1	CC_IN	1	0: CC_IN < 1.2 V 1: CC_IN > 1.5 V
0	DET	1	0: DET output is low 1: DET is output is high

FUNCTION ENABLE

Address: 12h

Reset Value: 8'b 0000_1000

Type: Read/Write

Bits	Name	Size	Description
7	Reserved	1	Do not use
6	DET I/O Control	1	DET pin is in Open/Drain Configuration DET pin is in Push/Pull Configuration
5	RES detection range setting	1	1: 10k to 2560 k 0: 1k to 256 k
4	GPIO control enable	1	1: enable 0: disable
3	Slow turn on control enable	1	1: enable 0: disable
2	MIC auto break out control enable	1	1: enable 0: disable
1	RES detection enable	1	1: enable; will be changed to '0' after low resistance detection 0: disable
0	Audio jack detection and configuration enable	1	1: enable; will be changed to '0' after audio jack detection and configuration 0: disable

When GPIO control mode (manual switch control) is enable. 'Switch control' register is changed to read only. It will reflect switch status. I²C slave address is

RES DETECTION PIN SETTING

Address: 13h

Reset Value: 8'b 0000_0000

Type: Read

Bits	Name	Size	Description
[7:3]	Reserved	5	Do not use
[2:0]	Pin selection	3	000: CC_IN 001: DP/R 010: DN_L 011: SBU1 100: SBU2 101: Do not use 111: Do not use

If RES detection pin is enable before setting PIN selection it will always do the CC_IN first. Recommend user to select the pin first before setting the RES detection pin enable.

RES VALUE

Address: 14h

Reset Value: 8'b 1111_1111

Type: Read

Bits	Name	Size	Description
[7:0]	Detected resistance value	8	0000_0000 : R < 1 k 1111_1111: R > 300 K

RES DETECTION THRESHOLD

Address: 15h

Reset Value: 8'b 0001_0110

Type: Read

Bits	Name	Size	Description
[7:0]	RES detection threshold	8	Selection by 1 K Ω per step if Reg 12h [5] = 0
			Selection by 10 K Ω per step if Reg 12h [5] = 0
			Default Value = 22 KΩ
			0000_0000: 1 ΚΩ /10 ΚΩ
			1111_1111: 256 ΚΩ / 2560 ΚΩ

RES DETECTION INTERVAL

Address: 16h

Reset Value: 8'b 0000_0000

Type: Read

Bits	Name	Size	Description
[7:2]	Reserved	6	Do not use
[1:0]	RES detection interval	2	00: Single 01: 100 mS 10: 1 S 11: 10 S

AUDIO JACK STATUS

Address: 17h

Reset Value: 8'b 0000 0001

Type: Read

Bits	Name	Size	Description			
[7:3]	Reserved	4	Do not use			
3	4pole	1	1: 4 Pole SBU2 to MIC, SBU1 to audio ground 0: others			
2	4pole	1	1: 4 Pole SBU1 to MIC, SBU2 to audio ground 0: others			
1	3 pole	1	1: 3 pole 0: others			
0	No audio accessory	1	No audio accessory Audio accessory attached			

RES DETECTION /AUDIO JACK DETECTION INTERRUPT FLAG

Address: 18h

Reset Value: 8'b 0000_0000

Type: Read Clear

Bits	Name	Size	Description		
[7:3]	Reserved	5	Do Not Use		
2	Audio jack detection and configuration	1	O: Audio jack detection and configuration has not occurred 1: Audio jack detection and configuration has occurred		
1	Low resistance occurred	1	Cow resistance has not occurred Low resistance has occurred		
0	Low resistance detection	1	Cow resistance has not occurred Low resistance has occurred		

RES /AUDIO JACK DETECTION INTERRUPT MASK

Address: 19h

Reset Value: 8'b 0000 0000

Type: Read Clear

Bits	Name	Size	Description		
[7:3]	Reserved	5	Do Not Use		
2	Audio jack detection and configuration	1	Mask Audio jack detection and configuration has occurred interrupt		
1	Low resistance occurred	1	1: Low resistance has occurred interrupt		
0	Low resistance detection	1	1: Low resistance detection has occurred interrupt		

AUDIO JACK DETECTION REG1 VALUE

Address: 1Ah

Reset Value: 8'b 1111_1111

Type: Read

Bits	Name	Size	Description	
[7:0]	Audio jack detection value	8	Resistance between SBU1 to SBU2	

AUDIO JACK DETECTION REG2 VALUE

Address: 1Bh

Reset Value: 8'b 1111_1111

Type: Read

Bits	Name	Size	Description
[7:0]	Audio jack detection value	8	Resistance between SBU2 to SBU1

MIC DETECTION THRESHOLD DATAO

Address: 1Ch

Reset Value: 8'b 0010_0000

Type: Read/Write

Bits	Name	Size	Description		
[7:0]	MIC detection threshold DATA0	8	MIC detection threshold DATA0		
			0010_0000: 300 mV		

MIC DETECTION THRESHOLD DATA1

Address: 1Dh

Reset Value: 8'b 1111_1111

Type: Read/Write

Bits	Name	Size	Description		
[7:0]	MIC detection threshold DATA1	8	MIC detection threshold DATA1		
			1111_1111: 2.4 V		

I2C RESET

Address: 1Eh

Reset Value: 8'b 0000_0000

Type: W/C

Bits	Name	Size	Description
[7:1]	Reserved	7	Reserved
0	I2C reset	1	0: default 1: I ² C reset

CURRENT SOURCE SETTING

Address: 1Fh

Reset Value: 8'b 0000_0111

Type: Write

Bits	Name	Size	Description
[7:4]	Reserved	4	Reserved
[3:0]	Current Source Setting	4	1111: 1500 μA 0111: 700 μA 0001: 100 μA 0000: invalid

APPLICATION INFORMATION

Over-Voltage Protection

FSA4480 features over-voltage protection (OVP) on receptacle side pins that switches off the internal signal routing path if the input voltage exceeds the OVP threshold.

If OVP is occurred, interrupt signal can be send by INT signal and FLAG data will provide information that which pin had OVP event.

Headset Detection

FSA4480 integrates headset unplug detection function by detecting the CC_IN voltage. The function is always active when device is enabling. DET will be high when CC_IN is low (CC_IN < 1.2 V). When CC_IN = High (CC_IN > 1.5 V), DET will be released to low.

	Device Disable	Device Enable
CC_IN < V _{TH_L} = 1.2 V	DET = 0	DET = 1
CC_IN > V _{TH_H} = 1.5 V	DET = 0	DET = 0

MIC Switch Auto-off Function

The function is active during control bit 0x12h bit[2] = 1. When CC_IN is high (CC_IN > 1.5 V) and L,R, Audio ground switches are under on status, MIC switch will be off and receptacle side pin will be connected to ground for 50 μ S first. Then it shows high–Z status under MIC switch is set on status.

Audio Ground Detection and Configuration

The function is active when control bit 0x12h bit[0] = 1 and R, L AGND switches are set to be on status. For type–C interface analog headset, the audio ground could be SBU1 pin or SBU2 pin. The function will provide autonomous detection and configuration to route MIC and audio ground signal accordingly.

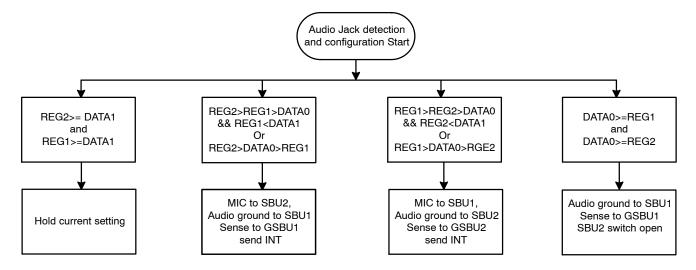


Figure 4.

During detection and configuration, the R, L, Sense, MIC and Audio ground switch will be off. After detection and configuration, R and L switches will turn on according to

switch configuration and timing setting. MIC, Sense and Audio ground will turn on according to detection results and timing control setting.

Resistance Detection

The function is active during control bit 0x12h bit[1] = 1. It will monitor the resistance between receptacle side pins and ground. During resistance detection, the switch which is monitored will be off. The detection result will be saved

in the resistance flag register. The measurement could be from 1 k Ω to 2.56 M Ω which is controlled by internal register. The detection interval can be set at 100 ms, 1 s or 10 s by register 0x16h.

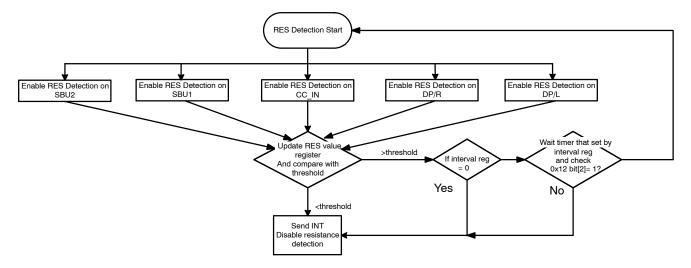


Figure 5.

Manual Switch Control

The function is active during control bit 0x12h bit[4] = 1 and 0x04h = FF. It will provide manual control for device.

During this configuration, ADDR and INT pins will be set as logic control input.

MANUAL SWITCH CONTROL

(The function is active during control bit 0x12h bit[4] = 1 and 0x04h = FF. It will provide manual control for device. During this configuration, ADDR and INT pins will be set as logic control input.)

Power	ENN	ADDR	INT	SENSE Switch	Headset Detection	USB Switch	Audio Switch	MIC/ Audio GND Switch	SBU by Pass Switch
OFF	Х	Х	Х	OFF	OFF	OFF	OFF	OFF	OFF
ON	Н	Х	Х	OFF	OFF	OFF	OFF	OFF	OFF
ON	L	0	0	OFF	OFF	ON: DP_R to DP DN_L to DN	OFF	OFF	ON: SBU1 to SBU1_H SBU2 to SBU2_H
ON	L	0	1	OFF	OFF	ON: DP_R to DP DN_L to DN	OFF	OFF	ON: SBU1 to SBU2_H SBU2 to SBU1_H
ON	L	1	0	ON GSBU2 to SESNE	ON	OFF	ON: DP_R to R DN_L to L	ON: SBU1 to MIC SBU2 to Audio GND	OFF
ON	L	1	1	ON GSBU1 to SESNE	ON	OFF	ON: DP_R to R DN_L to L	ON: SBU2 to MIC SBU1 to Audio GND	OFF

I²C INTERFACE

The FSA4480 includes a full I²C slave controller. The I²C slave fully complies with the I²C specification version 2.1

requirements. This block is designed for fast mode, 400 kHz, signals.

Examples of an I²C write and read sequence are shown in below figures respectively.



NOTE: Single Byte read is initiated by Master with P immediately following first data byte.

Figure 6. I²C Write Example

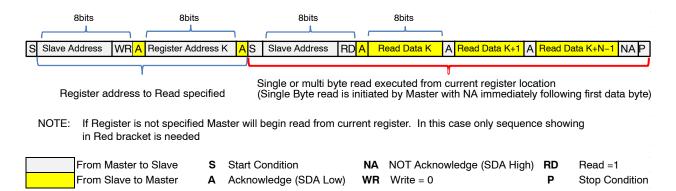


Figure 7. I²C Read Example

TEST DIAGRAMS

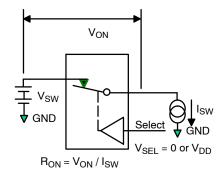
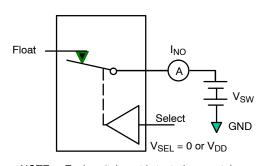


Figure 8. On Resistance



NOTE: Each switch port is tested separately.

Figure 9. Off Leakage (loz)

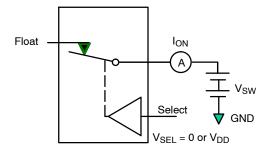
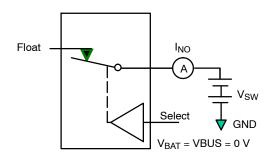


Figure 10. On Leakage



NOTE: Each switch port is tested separately.

Figure 11. Power Off Leakage (loff)

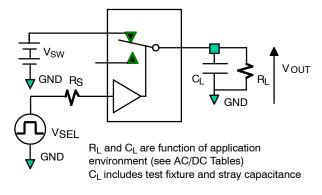


Figure 12. Test Circuit Load

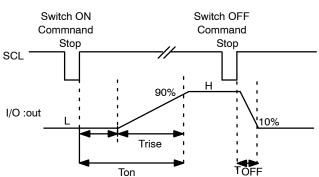


Figure 13. Turn On/Off Waveforms under Manual Mode

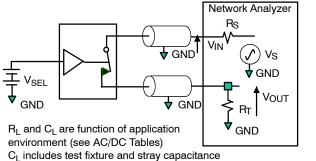


Figure 14. Bandwidth

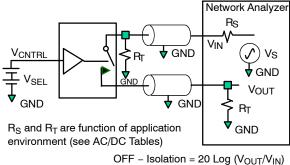


Figure 15. Channel Off Isolation

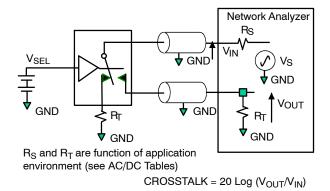


Figure 16. Adjacent Channel Crosstalk

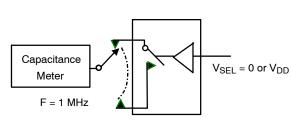


Figure 17. Channel Off Capacitance

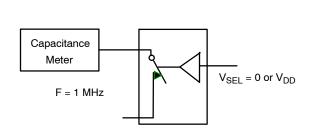


Figure 18. Channel On Capacitance

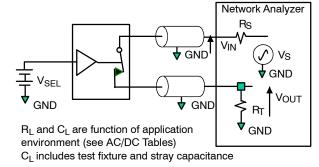


Figure 19. Total Harmonic Distortion (THD + N)

ORDERING INFORMATION

Part Number	Top Mark	Package	D	E	Х	Υ
FSA4480UCX	6D	25-Ball WLCSP	2.24mm	2.28mm	0.32mm	0.34mm

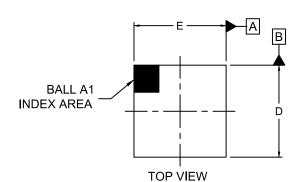
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WLCSP25 2.24x2.28x0.586

CASE 567UZ ISSUE B

DATE 03 JAN 2018

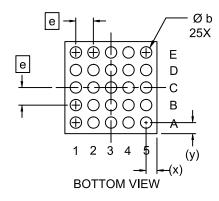


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

0.05 C	A2 A1 A1
SEATING PLANE	
SIDE VIEW	DETAIL A

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
Α	0.547	0.586	0.625
A1	0.178	0.208	0.238
A2	0.360	0.378	0.396
b	0.24	0.26	0.28
D	2.250	2.280	2.310
Е	2.210	2.240	2.270
е	0.40 BSC		
х	0.305	0.320	0.335
У	0.325	0.340	0.355



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RECOMMENDED	

RECOMMENDED MOUNTING FOOTPRINT (NSMD PAD TYPE)

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